

## Problem/Failure Report THM\_PFR\_104 F2 Backplane Damaged

Assembly: SN002 Backplane   SubAssembly:
Originator: Corinna Chen Organization: UCB SSL Themis Phone: 510.642.8030 Email: corinnac@ssl.berkeley.edu  Failure Occurred During (Check one √) □ Functional test □ Qualification test □ S/C Integration □ Launch operations √ Other (Flight Assy)  Environment when failure occurred:  √ Ambient □ Vibration □ Shock □ Acoustic □ Thermal □ Vacuum □ Thermal-Vacuum □ EMI/EMC  Problem Description  The hypertronics connector on the backplane SN002 had a bent pin and could no longer be used.
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I ha problem accurred during tipal accomply build at LACLIIIIII on V/III/II. I buring machanical accomply
the LVPS was misaligned with the chassis and there was difficulty in connecting to the backplane The
misalignment resulted in a bent pin on the hypertronics connector of the backplane.
initial ginitation resulted in a context pin on the hyperatories confidence of the cacaptaine.
Corrective Action/ Resolution
The FM2 backplane was decided unusable due to the special connector and the difficulty of removing the
connector without doing harm to the backplane board. SN018 backplane, slated to be FM6, was named the
new FM2 backplane. All documentation has been transferred to the FM2 backplane traveler. A new
backplane will be assembled for FM6.
Accomtonico
Acceptance: MAM: Ron Jackson ; MSE: Ellen Taylor
PM: Peter Harvey ; Cognizant Engineer
Date of Closure